

MATED CONDITION

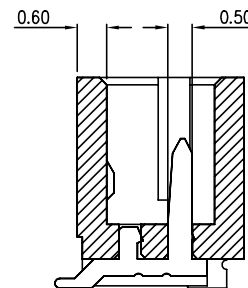
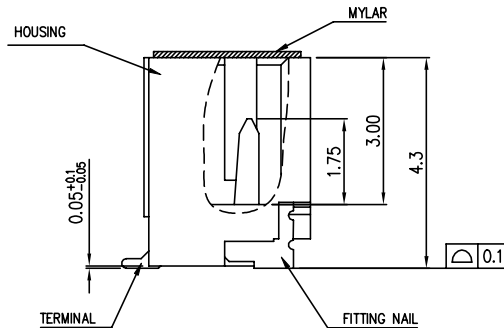
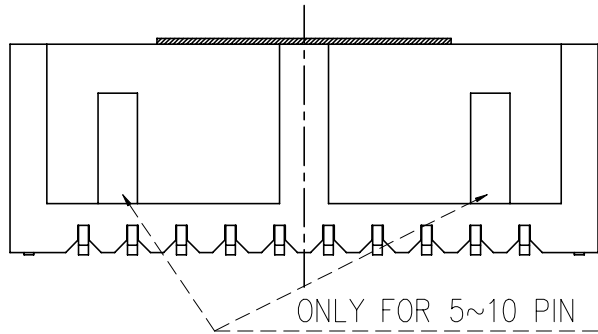
NOTES:

- 1.MATERIAL:
HOUSING:HALOGEN FREE PLASTIC,HI-TEMP,UL94V-0
TERMINAL: COPPER ALLOY
FITTING NAIL: COPPER ALLOY
- 2.FINISH
2.1 CONTACT
50u" MIN NICKEL UNDER PALTING OVERALL
N:120u" MIN MATT TIN OVERALL
1:GOLD FLASH ON CONTACT AND SOLDER AREA
D:30u" GOLD PLATING ON CONTACT POINT
AND GOLD FLASH ON SOLDER TAIL
C:30u"~80u" NICKEL OVERALL
15u" GOLD PLATING ON CONTACT AREA
AND GOLD FLASH ON SOLDER AREA
3:50u"~100u" NICKEL OVERALL
1u" GOLD PLATING ON CONTACT AND SOLDER AREA
- 2.2 FITTING NAIL
50u" MIN NICKEL UNDER PALTING OVERALL
N:120u" MIN MATT TIN OVERALL
- 3.COPLANARITY 0.1 MM MAX. BASE ON DATUM A
- 4.TRUE POSITION 0.1 MM MAX. BASE ON DATUM B
- 5.THE SPEC. PLS. REFER TO PS-50228-XXXX-XXX
- 6.THE PACKING DRAWING PLS. REFER TO 51290-XXXX-XX-TRP

P/N LEGEND

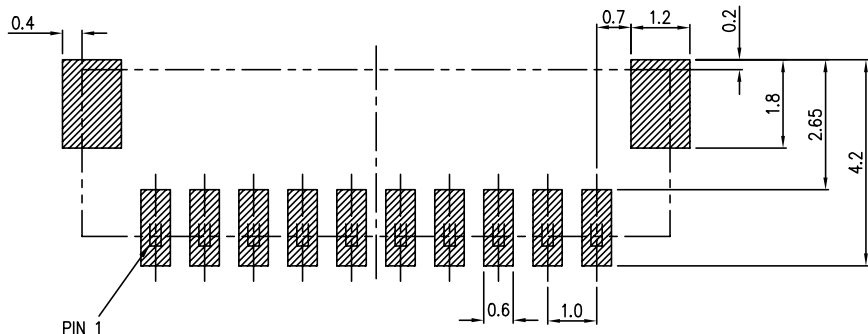
51290-XXX X X-XXX	XXX	HOUSING COLOR	PACKING
NO OF CKT	001	BLACK	51290-XXXXX-XX-TRP
PACKING	002	WHITE	51290-XXXXX-XX-TRP

PLATING
N:MATT TIN(LEAD FREE)
1:GOLD FLASH
C:15u" GOLD ON CONTACT FOR LEAD FREE
D:30u" GOLD ON CONTACT FOR LEAD FREE
3:1u" GOLD ON CONTACT AND SOLDER AREA

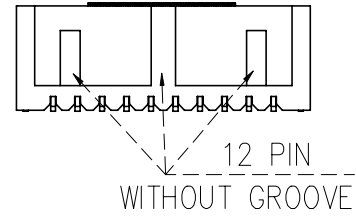


SECTION A-A

CKT	Dim A	Dim B	Dim C
6	5.0	6.4	8.0
7	6.0	7.4	9.0
8	7.0	8.4	10.0
9	8.0	9.4	11.0
10	9.0	10.4	12.0
11	10.0	11.4	13.0
12	11.0	12.4	14.0
14	13.0	14.4	16.0



PCB PATTERN LAYOUT (TOP VIEW)



QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY GaoLi CHECKED BY Xu,ZhiYong APPROVED BY Xu,ZhiYong	DATE 22/12/06 DATE 22/12/06 DATE 22/12/06	 1.0mm Pitch WTB Wafer Conn. SMT S/R S/T Type	
	UNITS mm SCALE 1:1	SIZE A4 SHEET NO. 1 OF 1		RFG NO. N/A REV DWG NO. 51290-XXXXX-XXX